



#### 60V PNP LOW VCESAT TRANSISTOR IN PowerDI3333-8

#### **Features**

- BV<sub>CEO</sub> > -60V
- Small Form Factor Thermally Efficient Package.
   Enables Higher Density End Products
- I<sub>C</sub> = -5.5A Continuous Collector Current
- I<sub>CM</sub> = -15A Peak Pulse Current
- Low Saturation Voltage V<sub>CE(sat)</sub> < 90mV @ -1A</li>
- h<sub>FE</sub> Specified Up to -10A for a High Gain Hold Up
- Complementary NPN Type: DXTN03060CFG
- Rated to +175°C Ideal For High Temperature Environment
- Wettable Flank For Improved Optical Inspection
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

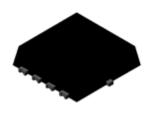
#### **Mechanical Data**

- Case: PowerDI<sup>®</sup>3333-8
- Case Material: Molded Plastic. "Green" Molding Compound.
   UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish—Matte Tin Plated Leads Solderable per MIL-STD-202, Method 208 63
- Weight: 0.03 grams (Approximate)

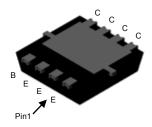
## **Applications**

- Motor Driving
- Line Switching
- High Side Switches

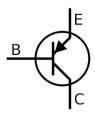
PowerDI3333-8 (SWP) (Type UX)







**Bottom View** 



Device Symbol

### Ordering Information (Note 4)

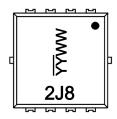
4					
	Part Number	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
	DXTP03060CFG-7	2,18	7	12	2000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/products/packages.html.

## **Marking Information**

PowerDI3333-8 (SWP) (Type UX)



2J8= Product Type Marking Code

YYWW = Date Code Marking

YY = Last Two Digits of Year (ex: 19 = 2019)

WW = Week Code (01 to 53)



## **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-70	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-60	V
Emitter-Base Voltage	V <sub>EBO</sub>	-7	V
Continuous Collector Current	Ic	-5.5	Α
Peak Pulse Current	I <sub>CM</sub>	-15	A

# Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
	(Note 5)		1.07	W
Power Dissipation	(Note 6)	P <sub>D</sub>	2.3	W
	(Note 7)		3.4	W
	(Note 5)		140	°C/W
Thermal Resistance, Junction to Ambient	(Note 6)	R <sub>OJA</sub>	65	°C/W
	(Note 7)		44	°C/W
Thermal Resistance, Junction to Leads (Note 8	$R_{\Theta JL}$	6	°C/W	
Operating and Storage Temperature Range	$T_{J,}T_{STG}$	-55 to +175	°C	

## ESD Ratings (Note 9)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	≥ 400	V	С

Notes:

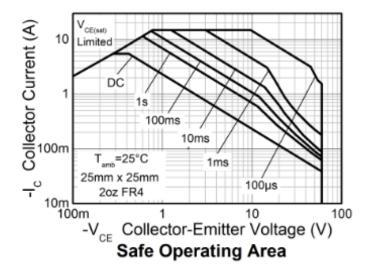
- 5. For a device mounted with the collector tab on MRP FR4-PCB; device is measured under still air conditions whilst operating in a steady-state.
  6. Same as Note 5, except the device is mounted on 25mm × 25mm 2oz copper.
  7. Same as Note 5, except the device is mounted on 50mm × 50mm 2oz copper.

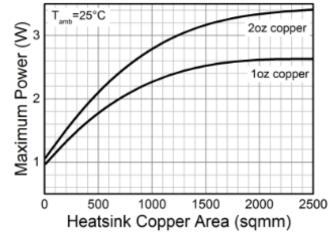
- 8. Thermal resistance from junction to solder-point (at the collector tab).

  9. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

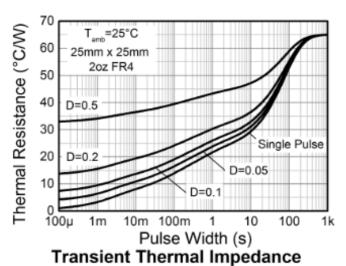


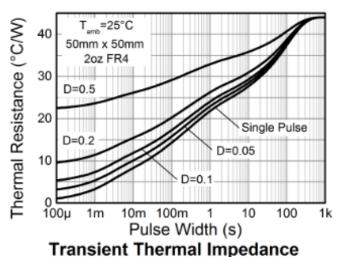
## **Thermal Characteristics and Derating Information**





Max Power Dissipation vs. Copper Area





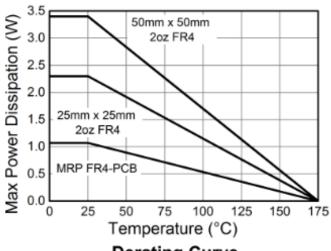
Single Pulse T<sub>amb</sub>=25°C

50mm x 50mm 20z FR4

100μ 1m 10m 100m 1 10 100 16

Pulse Width (s)

**Pulse Power Dissipation** 



**Derating Curve** 



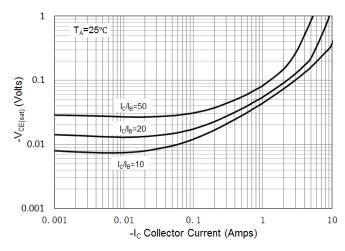
# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

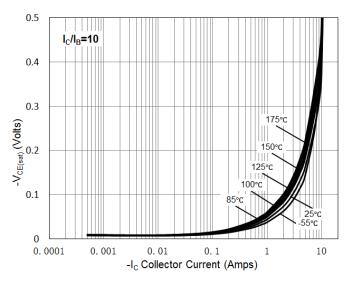
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	-70	-102	_	V	I <sub>C</sub> = -100μA
Collector-Emitter Breakdown Voltage (Note 10)	BV <sub>CEO</sub>	-60	-79	_	V	I <sub>C</sub> = -10mA
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	-7	-8.6	_	V	I <sub>E</sub> = -100μA
Collector-Base Cutoff Current	I <sub>CBO</sub>	_	-1	-50	nA	V <sub>CB</sub> = -70V
Collector-base Cutoff Current		_	-0.06	-10	μΑ	V <sub>CB</sub> = -70V, T <sub>A</sub> = +125°C
Callantar Fraitter Cutoff Current	I <sub>CER</sub>	_	-1	-50	nA	V <sub>CB</sub> = -60V
Collector-Emitter Cutoff Current	R ≤ 1kΩ	_	-1	-10	μA	V <sub>CB</sub> = -60V, T <sub>A</sub> = +125°C
Emitter Cutoff Current	I <sub>EBO</sub>	_	-1	-20	nA	V <sub>EB</sub> = -6V
		240	362	_	_	I <sub>C</sub> = -10mA, V <sub>CE</sub> = -2V
Static Forward Current Transfer Datic (Note 10)	L	200	308	800	_	I <sub>C</sub> = -1A, V <sub>CE</sub> = -2V
Static Forward Current Transfer Ratio (Note 10)	h <sub>FE</sub>	180	271	_	_	I <sub>C</sub> = -2A, V <sub>CE</sub> = -2V
		45	130	_	_	I <sub>C</sub> = -5A, V <sub>CE</sub> = -2V
		_	-12	-30	mV	I <sub>C</sub> = -100mA, I <sub>B</sub> = -10mA
Callacter Freitter Caturation Valtoria (Nate 40)	V <sub>CE(sat)</sub>	_	-44	-90	mV	I <sub>C</sub> = -1A, I <sub>B</sub> = -100mA
Collector-Emitter Saturation Voltage (Note 10)		_	-74	-150	mV	I <sub>C</sub> = -2A, I <sub>B</sub> = -200mA
		_	-161	-300	mV	I <sub>C</sub> = -5A, I <sub>B</sub> = -500mA
Base-Emitter Saturation Voltage (Note 10)	V <sub>BE(sat)</sub>	_	-995	-1.1	V	I <sub>C</sub> = -5A, I <sub>B</sub> = -500mV
Base-Emitter Turn-On Voltage (Note 10)	V <sub>BE(on)</sub>	_	-891	-1	V	I <sub>C</sub> = -5A, V <sub>CE</sub> = -1V
Output Capacitance	$C_{obo}$	_	48	_	pF	V <sub>CB</sub> = -10V. f = 1MHz
Transition Frequency	f <sub>T</sub>	_	120	_	MHz	$V_{CE} = -10V, I_{C} = -100mA$ f = 50MHz
	t <sub>delay</sub>	_	5	_	ns	
Switching Characteristics	t <sub>rise</sub>	_	300	_	ns	$V_{CC} = -10V, I_{C} = -1A$
Switching Characteristics	t <sub>storage</sub>	_	1486	_	ns	I <sub>B1</sub> = -I <sub>B2</sub> = -100mA
	t <sub>fall</sub>	_	191	_	ns	

Note: 10. Measured under pulsed conditions. Pulse width  $\leq$  300 $\mu$ s. Duty cycle  $\leq$  2%.



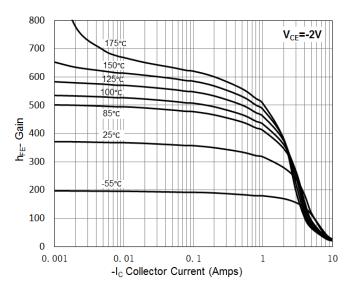
# Typical Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

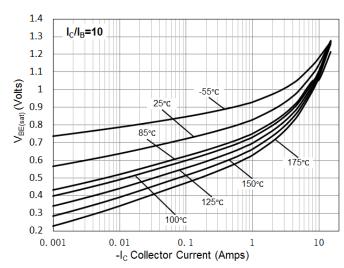




V<sub>CE(sat)</sub>vs I<sub>C</sub>

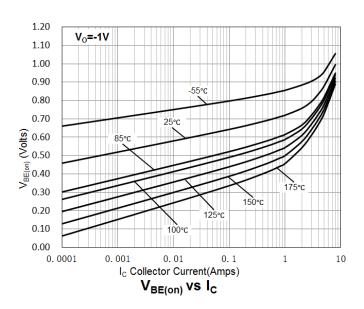
V<sub>CE(sat)</sub>vs I<sub>C</sub>





 $h_{\text{FE}} \text{ vs } I_{\text{C}}$ 

V<sub>BE(sat)</sub> vs I<sub>C</sub>

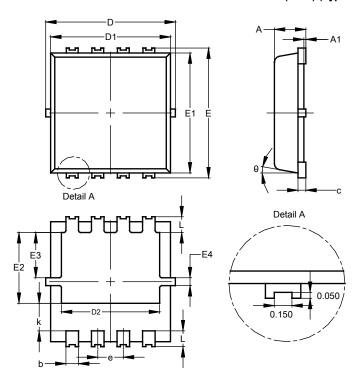




# **Package Outline Dimensions**

Please see https://www.diodes.com/package-outlines.html for the latest version.

### PowerDI3333-8 (SWP) (Type UX)

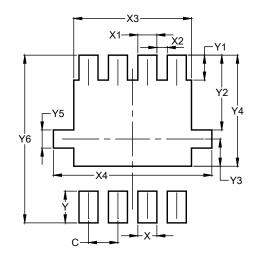


PowerDI3333-8 (SWP)					
(Type UX)					
Dim	Min	Max	Тур		
A	0.75	0.85	0.80		
A1	0.00	0.05	_		
b	0.25	0.40	0.32		
С	0.10	0.25	0.15		
D	3.20	3.40	3.30		
D1	2.95	3.15	3.05		
D2	2.30	2.70	2.50		
Е	3.20	3.40	3.30		
E1	2.95	3.15	3.05		
E2	1.60	2.00	1.80		
E3	0.95	1.35	1.15		
E4	0.10	0.30	0.20		
е	_	_	0.65		
k	0.50	0.90	0.70		
L	0.30	0.50	0.40		
θ	0°	12°	10°		
All Dimensions in mm					

# **Suggested Pad Layout**

Please see https://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI3333-8 (SWP) (Type UX)



Dimensions	Value (in mm)		
С	0.650		
X	0.420		
X1	0.420		
X2	0.230		
Х3	2.600		
X4	3.500		
Υ	0.700		
Y1	0.550		
Y2	1.650		
Y3	0.600		
Y4	2.450		
Y5	0.400		
Y6	3.700		

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device terminals and PCB tracking.



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